

WHAT IS CLAIMED IS

1. A buff process module, comprising:

a buff table on which a substrate is mounted;

a buff head configured to hold a buff pad for

applying a predetermined process to the substrate;

a buff arm that supports and swings the buff head;

a dresser for dressing the buff pad;

a cleaning mechanism for cleaning a surface of the buff pad;

wherein a groove is formed on the surface of the buff pad, and the cleaning mechanism includes an atomizer configured to supply a high pressure cleaning fluid to remove deposit in the groove,

wherein the atomizer is configured to supply the high pressure cleaning fluid while being positioned below the buff arm, and the atomizer is configured to clean a lower surface of the buff arm and the buff pad at the same time.

2. The buff process module according to claim 1, wherein the atomizer is disposed below a movement path of the buff pad that faces perpendicularly downward, and the atomizer is movable.

~~3. The buff process module according to claim 1, wherein the atomizer is configured to supply the high pressure cleaning fluid while being positioned below the buff arm, and the atomizer is configured to clean a lower surface of the buff arm and the buff pad at the same time.~~

~~43.~~ The buff process module according to claim 1, wherein

the atomizer includes a plurality of nozzles ~~mounted linearly~~
~~on the main body~~, and is configured to supply the high
pressure cleaning fluid.